Post Office Address: 608 Boise Hills Drive, Boise, ID 83702

ATTORNEY) TION FOR PATENT APPLICATION (WITH POWE"

As an inventor named below or on any attached continuation page, I hereby declare that:

My residence, post office address and citizenship are as stated next to my name.

I believe that I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled METHOD FOR IN-LINE TESTING OF FLIP-CHIP SEMICONDUCTOR ASSEMBLIES, the specification of which (check one):

語 is attached hereto U was filed onas U	Jnited States application serial no.	and was amended on			
	CT international application no.	and was amended under		, 	
					
I hereby state that I have reviewed referred to above.	and understand the contents of the above-	identified specification, inclu	ding the claims, as amend	ied by any an	nendm
	to the U.S. Patent and Trademark Office a materiality" is defined in Title 37, Code o		-	ntability of th	e subj
certificate or § 365(a) of any PCT inter	efits under Title 35, United States Code, § mational application(s) designating at least	one country other than the l	United States of America	listed below	and or
	to identified below and on any attached co signating at least one country other than the med.				ificate
Prior foreign/PCT application(s):			•		
				Priority C	laimed
(number)	(country)	(day/month/year filed)	Yes	N
(number)	(country)		day/month/year filed)	Yes	N
	e 35, United States Code, § 120 of any U a listed below and on any attached continu				
(application serial no.)	(filing date)	(status	- pending, patented or ab	andoned)	·
(abbusered series man)	(11111)	(0-1-2)	pointing, parameter and additional		
(application serial no.)	(filing date)	(status	- pending, patented or ab	andoned)	
I hereby claim the	benefit under Title 35, United States Code	. § 119(e) of any United Sta	ites provisional application	n(s) listed hel	ow.
					·
(provisional application no.)	(filing date)			•	•
(provisional application no.)	(filing date)	•	,		
Greensen approximation	(,				
(provisional application no.)	(filing date)				
I hereby appoint the following Registe nnected therewith:	red Practitioners to prosecute this applicat	ion and to transact all busine	ess in the Patent and Trad	lemark Office	,
David V. Trask, Reg. No. 22,012	William S. Britt, Reg. No. 20,96	9 Thomas I	Rossa, Reg. No. 26,799		
Laurence B. Bond, Reg. No. 30,549	Joseph A. Walkowski, Reg. No.	28,765 James R. D	uzan, Reg. No. 28,393		
Allen C. Turner, Reg. No. 33,041 Robert G. Winkle, Reg. No. 37,474	Kent S. Burningham, Reg. No. 39,29 Patrick McBride, Reg. No. 39,29		orriss, Reg. No. 33,263		
Brick G. Power, Reg. No. 38,581	Kenneth C. Booth, Reg. No. 43,3		ataxinos, Reg. No. 39,93 Lynch, Reg. No. 30,871		
Lia M. Pappas, Reg. No. 34,095					
	Joseph A. Walkowski, telephone no. (801) FRASK, BRITT & ROSSA	532-1922.		•	٠,
	P.O. BOX 2550				
5	Salt Lake City, Utah 84110			•	
I hereby declare that all statements mad	e herein of my own knowledge are true a	nd that all statements made	on information and belief	are believed	to he
e; and further that these statements were	made with the knowledge that willful fal-	se statements and the like so	made are punishable by	fine or impris	sonne
both, under Section 1001 of Title 18 of ent issued thereon.	the United States Code and that such willi	ful false statements may jeop	pardize the validity of the	application o	rany
I name of first joint inventor: Chad A.	Gobbley	a/	0 /00		
entor's signature	filler	Date	3/98		
sidence: Boise, Idaho izenship: USA			•		

DECLARATION FOR PATENT APPLICATION

(continuation page)

Invention title: METHOD FOR IN-LINE TESTING OF FLIP-CHIP SEMICONDUCTOR ASSEMBLIES Inventor name(a) appearing on first declaration page: Chad A. Cobbley Additional original, first and joint inventor(s): Full name of second joint inventor: John VanNortwick Inventor's signature Residence: Kuna, Idaho Citizenship: USA Post Office Address: 186 South Ash, Kuna, ID 83634 Full name of third joint inventor: Bret K. Street Date Inventor's signature Residence: Meridian, Idaho Citizenship: USA Post Office Address: 1366 North Rutledge Avenue, Meridian, ID 83642 Full name of fourth joint inventor: Tongbi Jiang 9130198 Date

Inventor's signature

Residence: Boise, Idaho

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: Cobbley et al.

Serial No.: 09/819,472

Filed: March 28, 2001

For: METHOD FOR IN-LINE TESTING OF FLIP-CHIP SEMICONDUCTOR

ASSEMBLIES

Confirmation No.: 3718

Examiner: R. Kobert

Group Art Unit: 2829

Attorney Docket No.: 2269-3437.2US

CERTIFICATE OF MAILING

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail on the date of deposit shown below with sufficient postage and in an envelope addressed to the Commissioner for Patents, Washington, D.C. 20231.

January 8, 2003

Organicare

Amanda Holland
Name (Type/Print)

ASSOCIATE POWER OF ATTORNEY

Commissioner for Patents Washington, D.C. 20231

Sir:

In accordance with 37 C.F.R. § 1.34(b), please recognize the following individual as an associate agent/attorney herein in connection with the above-identified patent application, and with all continuing and divisional applications hereof:

Kevin K. Johanson, Reg. No. 38,506

Respectfully submitted,

Joseph A. Walkowski Registration No. 28,765 Attorney for Applicant(s)

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Date: January 8, 2003

JAW/ah

Document in ProLaw